

Claims:

1. A ferroelectric device, comprising:
a prestress layer placed on a mold;
5 a ferroelectric layer placed on the prestress layer, such that a layered structure is created;
means for heating the prestress and ferroelectric layers; and
means for cooling the prestress and ferroelectric layers such that the heating and cooling means induce a prestress into the layered structure.
- 10 2. The method of claim 1, wherein the prestress layer includes reinforcing material.
- 15 3. The method of claim 1 wherein the ferroelectric layer includes surface electrodes.
4. The method of claim 1, further comprising:
an electrode layer placed between the prestress layer and the ferroelectric layer; and
20 an electrode layer placed on top of the ferroelectric layer.
5. The method of claim 1 wherein the prestress layer is an adhesive.
- 25 6. The method of claim 1 wherein the ferroelectric layer is a piezoelectric material.
7. The method of claim 1 wherein the ferroelectric layer is a piezoelectric material.
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8. ~~The method of claim 1 wherein the ferroelectric layer is formed from a composite.~~

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